JSCJ

MSDS Report

Report NO.: M000004000001

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJU15SN10
Package Type :	TO-252-2L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.0000%	0.8850%
Lead Frame	Iron	7439-89-6	0.1000%	57.9454%
	Phosphorus	7723-14-0	0.2125%	
	Copper	7440-50-8	99.6834%	
	Nickel (Ni)	7440-02-0	0.0041%	
Soft Solder	Lead	7439-92- 1	92.5000%	1.1132%
	Tin	7440-31-5	5.0000%	
	Silver	7440-22-4	2.5000%	
Wire1	Al	7429-90-5	99.9960%	0.2796%
	Ni	7440-02-0	0.0008%	
	Si	7440-21-3	0.0008%	
	Fe	7439-89-6	0.0008%	
	Mg	7439-95-4	0.0003%	
	Cu	7440-50-8	0.0007%	
	Other	Trade secret	0.0006%	
Wire2	Copper	7440-50-8	99.9920%	0.0029%
	Calcium	7440-70-2	0.0018%	
	Aluminum	7429-90-5	0.0018%	
	Silver	7440-22-4	0.0016%	
	Others	/	0.0028%	
Mold Compound	Silica	60676-86-0	75.5000%	38.4906%
	Epoxy Resin	29690-82-2	13.0000%	
	Phenol Resin	9003-35-4	8.0000%	
	Fire Retardant	Trade secret	3.0000%	
	Carbon black	1333-86-4	0.5000%	
Plating	Tin	7440-31-5	99.9900%	1.2834%
	Other	/	0.0100%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.